| Ref # | Hits | Search Query | DBs | Default Operator | Plurals | Time Stamp |
|---|---|---|---|---|---|---|
| S1 | 338 | 703/13.ccor. | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:35 |
| S2 | 548 | 703/14.ccor. | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:35 |
| S3 | 186 | 703/15.ccor. | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:35 |
| S4 | 83 | 703/16.ccor. | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:36 |
| S5 | 106 | 703/17.ccor. | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:36 |
| S6 | 5 | (("5754826") or ("5923567") or ("6197605") or ("6768983") or ("6891626")).PN. | US-PGPUB; USPAT | OR | OFF | 2006/02/02 17:43 |
| S7 | 24 | optical adj digital adj profil$ | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:43 |
| S8 | 4 | S7 and @ad<="20020228" | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:43 |
| S9 | 70 | Specular adj Spectroscopic adj Scatterometry | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:46 |
| S10 | 31 | S9 and @ad<="20020228" | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:47 |
| S11 | 37586 | (integrated adj circuit) and simulat$4 | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:47 |
| S12 | 7010 | S11 and profil$ | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:47 |
| S13 | 489 | S12 and metrology | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:48 |
| S14 | 408 | S13 and fabricat$4 | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:48 |
| S15 | 75 | S14 and attribute | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:48 |
| S16 | 24 | S15 and @ad<="20020228" | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:49 |
| S17 | 13791 | critical adj dimension | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:49 |
| S18 | 6844 | S17 and shape | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:50 |
| S19 | 38 | S15 and S18 | US-PGPUB; USPAT | OR | ON | 2006/02/02 17:53 |
| S20 | 5 | S19 and @ad<="20020228" | US-PGPUB; USPAT | OR | ON | 2006/02/02 18:02 |
| S21 | 5 | ("4342090" \| "4949275" \| "5313398" \| "5355320" \| "5379237").PN. | US-PGPUB; USPAT; USOCR | OR | ON | 2006/02/02 19:08 |
| S22 | 71 | ("5539652").URPN. | USPAT | OR | ON | 2006/02/02 19:23 |

| | | Results |
|---|---|---|
| 13. | ((((((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter) and device) and circuit) and amplifier<br>*[All Sources(- All Sciences -)]* | 7 |
| 12. | ((((((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter) and device) and circuit) and interconnect<br>*[All Sources(- All Sciences -)]* | 7 |
| 11. | (((((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter) and device) and circuit<br>*[All Sources(- All Sciences -)]* | 40 |
| 10. | ((((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter) and device<br>*[All Sources(- All Sciences -)]* | 40 |
| 9. | ((((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter) and attribute<br>*[All Sources(- All Sciences -)]* | 5 |
| 8. | (((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile) and parameter<br>*[All Sources(- All Sciences -)]* | 55 |
| 7. | ((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit) and profile<br>*[All Sources(- All Sciences -)]* | 62 |
| 6. | (pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)) and integrated circuit<br>*[All Sources(- All Sciences -)]* | 145 |
| 5. | pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(metrology)<br>*[All Sources(- All Sciences -)]* | 1732 |
| 4. | (((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(critical dimension)) and profile) and parameter) and attribute<br>*[All Sources(- All Sciences -)]* | 21 |
| 3. | ((pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(critical dimension)) and profile) and parameter<br>*[All Sources(- All Sciences -)]* | 255 |
| 2. | (pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(critical dimension)) and profile<br>*[All Sources(- All Sciences -)]* | 318 |
| 1. | pub-date > 1959 and pub-date < 2003 and FULL-TEXT(simulat!) and FULL-TEXT(critical dimension)<br>*[All Sources(- All Sciences -)]* | 1059 |

Fri, 3 Feb 2006, 6:53:51 PM EST

Edit an existing query or compose a new query in the Search Query Display.

**Select a search number (#) to:**

- Add a query to the Search Query Display
- Combine search queries using AND, OR, or NOT
- Delete a search
- Run a search

**Search Query Display**

[redacted]

| Recent Search Queries | | Results |
|---|---|---|
| #1 | ((integrated circuit<and>simulat*)<and>profile) <and> (pyr >= 1951 <and> pyr <= 2002) | 5977 |
| #2 | ((attribute<and>metrology)<and>parameter) <and> (pyr >= 1951 <and> pyr <= 2002) | 376 |
| #3 | (((integrated circuit<and>simulat*)<and>profile) <and> (pyr >= 1951 <and> pyr <= 2002)) <AND> (((attribute<and>metrology) <and>parameter) <and> (pyr >= 1951 <and> pyr <= 2002)) | 42 |
| #4 | ((fabrication<and>critical dimension)<and>shape) <and> (pyr >= 1951 <and> pyr <= 2002) | 182 |
| #5 | ((((integrated circuit<and>simulat*)<and>profile) <and> (pyr >= 1951 <and> pyr <= 2002)) <AND> (((attribute<and>metrology) <and>parameter) <and> (pyr >= 1951 <and> pyr <= 2002))) <AND> (((fabrication<and>critical dimension)<and>shape) <and> (pyr >= 1951 <and> pyr <= 2002)) | 5 |

[redacted]

Published before March 2002
Terms used metrology profile

Found 7 of 125,146

Sort results by relevance
Display results condensed form

Save results to a Binder
Search Tips
Open results in a new window

Try an Advanced Search
Try this search in The ACM Guide

Results 1 - 7 of 7

Relevance scale

1 Putting the U.S. standardization system into perspective: new insights
Bob Toth
December 1996 **StandardView**, Volume 4 Issue 4
Publisher: ACM Press
Full text available: pdf(172.91 KB) Additional Information: full citation, abstract, references, index terms

2 All digital built-in delay and crosstalk measurement for on-chip buses
Chauchin Su, Yue-Tsang Chen, Mu-Jeng Huang, Gen-Nan Chen, Chung-Len Lee
January 2000 **Proceedings of the conference on Design, automation and test in Europe**
Publisher: ACM Press
Full text available: pdf(168.37 KB) Additional Information: full citation, references, index terms
Publisher Site

3 An automated documentation system for a large scale manufacturing engineering research project
Howard M. Bloom, Carl E. Wenger
April 1983 **Proceedings of the 2nd annual international conference on Systems documentation**
Publisher: ACM Press
Full text available: pdf(637.00 KB) Additional Information: full citation, abstract, references, index terms

4 Supporting valid-time indeterminacy
Curtis E. Dyreson, Richard Thomas Snodgrass
March 1998 **ACM Transactions on Database Systems (TODS)**, Volume 23 Issue 1
Publisher: ACM Press
Full text available: pdf(516.09 KB) Additional Information: full citation, abstract, references, citings, index terms

5 Kinematic tolerance analysis
Leo Joskowicz, Elisha Sacks, Vijay Srinivasan
December 1995 **Proceedings of the third ACM symposium on Solid modeling and applications**
Publisher: ACM Press
Full text available: pdf(943.98 KB) Additional Information: full citation, references, citings, index terms

6 Verification, validation & accreditation (panel): disciplines in dialogue or can we learn from the experiences of others?
James D. Arthur, Richard E. Nance, Robert G. Sargent, Dolores R. Wallace, Linda H. Rosenberg, Paul R. Muessig
December 1997 **Proceedings of the 29th conference on Winter simulation**
Publisher: ACM Press
Full text available: pdf(806.49 KB) Additional Information: full citation, index terms

7 Contents of the Computer Communication Review 1970–1994
David Oran
January 1995 **ACM SIGCOMM Computer Communication Review**, Volume 25 Issue 1
Publisher: ACM Press
Full text available: pdf(1.75 MB) Additional Information: full citation, index terms

Results 1 - 7 of 7

Published before March 2002
Terms used profile simulation critical dimension

Found 5 of 125,146

Sort results by relevance
Display results condensed form
Save results to a Binder
Search Tips
Open results in a new window

Try an Advanced Search
Try this search in The ACM Guide

Results 1 - 5 of 5

Relevance scale

1 Substrate modeling and lumped substrate resistance extraction for CMOS ESD/latchup circuit simulation
Tong Li, Ching-Han Tsai, Elyse Rosenbaum, Sung-Mo Kang
June 1999 **Proceedings of the 36th ACM/IEEE conference on Design automation**
Publisher: ACM Press
Full text available: pdf(846.62 KB) Additional Information: full citation, references, index terms

2 Analysis and optimization of thermal issues in high-performance VLSI
Kaustav Banerjee, Massoud Pedram, Amir H. Ajami
April 2001 **Proceedings of the 2001 international symposium on Physical design**
Publisher: ACM Press
Full text available: pdf(320.70 KB) Additional Information: full citation, abstract, references, citings, index terms

3 Your core— my problem? (panel session): integration and verification of IP
Gabe Moretti, Tom Anderson, Janick Bergeron, Ashish Dixit, Peter Flake, Tim Hopes, Ramesh Narayanaswamy
June 2001 **Proceedings of the 38th conference on Design automation**
Publisher: ACM Press
Full text available: pdf(129.32 KB) Additional Information: full citation, abstract, index terms

4 Graphic applications to aerospace structural design problems
A. L. Eshleman, H. D. Meriwether
January 1967 **Proceedings of the 4th conference on Design automation**
Publisher: ACM Press
Full text available: pdf(1.55 MB) Additional Information: full citation, abstract, references, citings, index terms

5 Survey of image quality measurements
Ikram E. Abdou, Nicolas J. Dusaussoy
November 1986 **Proceedings of 1986 ACM Fall joint computer conference**
Publisher: IEEE Computer Society Press
Full text available: pdf(1.12 MB) Additional Information: full citation, references, index terms

Results 1 - 5 of 5

CiteSeer Find: integrated circuit and simulate and Documents Citations

Searching for **integrated circuit and simulate and metrology**.
Restrict to: Header Title Order by: Expected citations Hubs Usage Date Try: Google (CiteSeer) Google (Web) Yahoo! MSN CSB DBLP
2 documents found. **Order: number of citations.**

Models of Process Variations in Device and Interconnect - Duane Boning And (2000) (Correct) (4 citations)
performance of microprocessors or other **integrated circuits** are impacted bytwo sources of variation.
device model parameters needed to **simulate** the behavior of the design in a detailed circuit
Fourth Int. Workshop on Statistical **Metrology**, pp. 10-13, June 1999. 17] T. Park, T.
www-mtl.mit.edu/Metrology/PAPERS/MPU-long.pdf

Implementation Of An Automated Interface For Integration Of - Tcad With Semiconductor (2002) (Correct)
sequential steps occur in a standard **integrated circuit** development and production flow. Design:
etc.It is now standard to use ECAD tools to **simulate** the behavior of any schematic design of an
or sheet resistances are measured by using **metrology** tools on wafer level. The first three subjects
www.scs-europe.org/services/ess2002/PDF/meth-7.pdf

Try your query at: Google (CiteSeer) Google (Web) Yahoo! MSN CSB DBLP

CiteSeer Find: integrated circuit and simulation an Documents Citations

Searching for **integrated circuit and simulation and profile**.
Restrict to: Header Title Order by: Expected citations Hubs Usage Date Try: Google (CiteSeer) Google (Web) Yahoo! MSN CSB DBLP
11 documents found. **Order: number of citations.**

A Simulation Tool for Dynamically Reconfigurable Field.. - Lysaght, Stockwood (1996) (Correct) (20 citations)
and program complex, high-speed, digital **integrated circuits** within their own work environments.
1 A **Simulation** Tool For Dynamically Reconfigurable Field
also require less external memory for storage. The **profile** of the circuitry that is active on the array
drl4.eee.strath.ac.uk/papers/pl_ieee96.ps.Z

**One or more of the query terms is very common - only partial results have been returned. Try Google (CiteSeer).**

Extraction of Circuit Models for Substrate Cross-talk - Smedes, van der Meijs, van .. (1995) (Correct) (15 citations)
realization of densely packed (mixed signal) **integrated circuits** is prevention of cross-talk via the
and currents in the substrate, either by **simulation** of a 3D resistance mesh of the complete
The resistivity varies, because of the doping **profile**, only in the direction perpendicular to the
donau.et.tudelft.nl/pub/space/doc/1995/iccad95.ps.Z

Simulation-based Performance Analysis of Distributed Systems - Schwarz, al. (1997) (Correct) (3 citations)
Ulrich Donath Fraunhofer-Institute for **Integrated Circuits** Design Automation Department Zeunerstrasse
time-consuming method is the construction of a **simulation** model which includes the different subsystems,
subsystems, the communication system, and the load **profile**. In particular, this approach seems to be very
www.eas.iis.fhg.de/sim/publications/papers/1997/006/paper.ps.gz

REDO - Random Excitation and Deterministic.. - Grimaila, Lee.. (1999) (Correct) (2 citations)
term defects to denote actual flaws in an **integrated circuit**, which introduce erroneous operation for
ATPG process [FERG91]In this case, the fault **simulation** engine is modified to allow the **simulation** of
process. Specifically, each site's fault detection **profile** is lost in modern fault simulators because they
dropzone.tamu.edu/techpubs/./1999/ece9902.ps.gz

Finite Element Resolution Of The 3d Stationary.. - Pena, Bruguera, Zapata (1997) (Correct) (1 citation)
devices is an essential tool for **integrated circuit** designers. These simulators lead to an
mapping problem. 1 Introduction The numerical **simulation** of semiconductor devices is an essential tool
electron and hole concentrations and the doping **profile**, and R is the recombination-generation rate.
ftp.ac.uma.es/pub/reports/1997/UMA-DAC-97-01.ps.gz

Efficient Electrostatic and Electromagnetic Simulation Using.. - Kapur, Long (Correct)
are often used to extract models of **integrated circuit** structures. This extraction involves
Efficient Electrostatic and Electromagnetic **Simulation** Using IES 3 Sharad Kapur David E. Long Bell
material variations (e.g.the doping **profile** of a MOSFET)the differential approach is
www.bell-labs.com/user/kapur/Papers/ieee98.ps.gz

PARTICS: A PARallel Taskfarm for Integrated Circuit.. - Gaston, Alexander.. (Correct)
PARTICS :A PARallel Taskfarm for **Integrated Circuit** Simulators G.J. Gaston, W.J.C. Alexander,
for performing CPU intensive process and device **simulations**. The system gives an almost linear speed up is
more CPU intensive. The structure and doping **profile** calculated by process **simulation**, provide
ftp.epcc.ed.ac.uk/pub/tr/91/tr9108.ps.Z

Modeling And Simulation Of High Speed Interconnects - Biswas (1998) (Correct)
Chapter 1 Introduction 1.1 Motivation As **integrated circuit** processing technology marches relentlessly
Modeling And **Simulation** Of High Speed Interconnects By Baribrata
CMOS Inverter. 10 3.3 Vertical **Profile** of a two layer metal and a single layer poly
www.i3s.leeds.ac.uk/homes/MBS/vitae_theses/biswas_ms_1998.pdf

Compact Model Specification of RF MOSFET with DC and AC Evaluations - Kolding (1999) (Correct)
to fully exploit the flexibility inherent to **integrated circuit** design. Most CMOS manufacturing facilities
MOSFET layout can be used to give better **simulation** results by including layoutdependent
transistor into inversion [30]Hence, the doping **profile** of the well changes with depth making analysis
www.tele.auc.dk/risc/resource/r991005.pdf

Try your query at: Google (CiteSeer) Google (Web) Yahoo! MSN CSB DBLP